

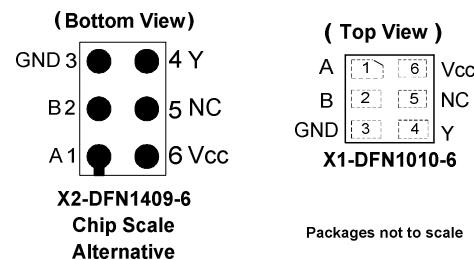
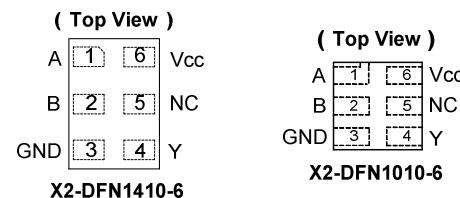
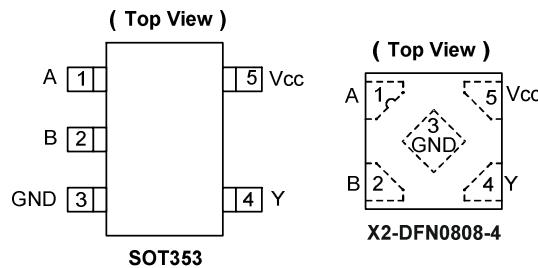
Description

The Advanced Ultra Low Power (AUP) CMOS logic family is designed for low power and extended battery life in portable applications.

The 74AUP1G00 is a single two-input positive NAND gate with a standard push-pull output designed for operation over a power supply range of 0.8V to 3.6V. The device is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing damaging current backflow when the device is powered down. The gate performs the positive Boolean function:

$$Y = \overline{A} \cdot \overline{B} \text{ or } Y = \overline{A} + \overline{B}$$

Pin Assignments



Packages not to scale

Features

- Advanced Ultra Low Power (AUP) CMOS
- Supply Voltage Range from 0.8V to 3.6V
- ± 4 mA Output Drive at 3.0V
- Low Static Power Consumption
 $I_{CC} < 0.9\mu A$
- Low Dynamic Power Consumption
 $C_{PD} = 6pF$ (Typical at 3.6V)
- Schmitt Trigger Action at all inputs makes the circuit tolerant for slower input rise and fall time. The hysteresis is typically 250mV at $V_{CC} = 3.0V$.
- I_{OFF} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
2000-V Human Body Model (A114)
Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Leadless Packages Named per JESD30E
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Applications

- Suited for Battery and Low Power Needs
- Wide array of products such as:
 - Tablets, E-readers
 - Cell Phones, Personal Navigation / GPS
 - MP3 Players, Cameras, Video Recorders
 - PCs, Ultrabooks, Notebooks, Netbooks
 - Computer Peripherals, Hard Drives, SSDs, CD/DVD ROMs
 - TVs, DVDs, DVRs, Set-Top Boxes

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Ordering Information

Logic Device	Function	Package	Packing
74 : Logic Prefix	00 : 2-Input	SE : SOT353	-7 : 7" Tape & Reel
AUP : 0.8 to 3.6 V	NAND Gate	FS3 : X2-DFN0808-4	
Logic Family		FW5 : X1-DFN1010-6	
1G : One Gate		FW4 : X2-DFN1010-6	
		FX4 : X2-DFN1409-6	
		FZ4 : X2-DFN1410-6	

Device	Package Code	Package (Notes 4 & 5)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74AUP1G00SE-7	SE	SOT353	2.0mm x 2.0mm x 1.1mm 0.65 mm lead pitch	3,000/Tape & Reel	-7
74AUP1G00FS3-7	FS3	X2-DFN0808-4	0.8mm x 0.8mm x 0.35mm 0.5 mm pad pitch (diamond)	5,000/Tape & Reel	-7
74AUP1G00FW5-7	FW5	X1-DFN1010-6	1.0mm x 1.0mm x 0.5mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74AUP1G00FW4-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74AUP1G00FX4-7	FX4	X2-DFN1409-6 Chip Scale Alternative	1.4mm x 0.9mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7
74AUP1G00FZ4-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7

Notes: 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

5. The taping orientation is located on our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Pin Descriptions

Pin Name	Function
A	Data Input
B	Data Input
GND	Ground
Y	Data Output
V _{CC}	Supply Voltage

Logic Diagram



Function Table

Inputs		Output
A	B	Y
L	L	H
L	H	H
H	L	H
H	H	L

Absolute Maximum Ratings (Notes 6 & 7) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
V_{CC}	Supply Voltage Range	-0.5 to +4.6	V
V_I	Input Voltage Range	-0.5 to +4.6	V
V_O	Voltage Applied to Output in High or Low State	-0.5 to V_{CC} +0.5	V
I_{IK}	Input Clamp Current $V_I < 0$	50	mA
I_{OK}	Output Clamp Current ($V_O < 0$)	50	mA
I_O	Continuous Output Current ($V_O = 0$ to V_{CC})	±20	mA
I_{CC}	Continuous Current Through V_{CC}	50	mA
I_{GND}	Continuous Current Through GND	-50	mA
T_J	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature	-65 to +150	°C

- Notes:
- 6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommended values.
 - 7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 8) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit	
V_{CC}	Operating Voltage	0.8	3.6	V	
V_I	Input Voltage	0	3.6	V	
V_O	Output Voltage	0	V_{CC}	V	
I_{OH}	High-Level Output Current	$V_{CC} = 0.8\text{V}$	—	-20	μA
		$V_{CC} = 1.1\text{V}$	—	-1.1	mA
		$V_{CC} = 1.4\text{V}$	—	-1.7	
		$V_{CC} = 1.65\text{V}$	—	-1.9	
		$V_{CC} = 2.3\text{V}$	—	-3.1	
		$V_{CC} = 3.0\text{V}$	—	-4	
I_{OL}	Low-Level Output Current	$V_{CC} = 0.8\text{V}$	—	20	μA
		$V_{CC} = 1.1\text{V}$	—	1.1	mA
		$V_{CC} = 1.4\text{V}$	—	1.7	
		$V_{CC} = 1.65\text{V}$	—	1.9	
		$V_{CC} = 2.3\text{V}$	—	3.1	
		$V_{CC} = 3.0\text{V}$	—	4	
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 0.8\text{V}$ to 3.6V	—	200	ns/V
T_A	Operating Free-Air Temperature	-40	125	°C	

- Note: 8. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V _{CC}	T _A = +25°C		T _A = -40°C to +85°C		Unit
				Min	Max	Min	Max	
V _{IH}	High-Level Input Voltage	—	0.8V to 1.65V	0.80 x V _{CC}	—	0.80 x V _{CC}	—	V
		—	1.65V to 1.95V	0.65 x V _{CC}	—	0.65 x V _{CC}	—	
		—	2.3V to 2.7V	1.6	—	1.6	—	
		—	3.0V to 3.6V	2.0	—	2.0	—	
V _{IL}	Low-Level Input Voltage	—	0.8V to 1.65V	—	0.30 x V _{CC}	—	0.30 x V _{CC}	V
		—	1.65V to 1.95V	—	0.35 x V _{CC}	—	0.35 x V _{CC}	
		—	2.3V to 2.7V	—	0.7	—	0.7	
		—	3.0V to 3.6V	—	0.9	—	0.9	
V _{OH}	High-Level Output Voltage	I _{OH} = -20µA	0.8V to 3.6V	V _{CC} - 0.1	—	V _{CC} - 0.1	—	V
		I _{OH} = -1.1mA	1.1V	0.75 x V _{CC}	—	0.7 x V _{CC}	—	
		I _{OH} = -1.7mA	1.4V	1.11	—	1.03	—	
		I _{OH} = -1.9mA	1.65V	1.32	—	1.3	—	
		I _{OH} = -2.3mA	2.3V	2.05	—	1.97	—	
		I _{OH} = -3.1mA		1.9	—	1.85	—	
		I _{OH} = -2.7mA	3V	2.72	—	2.67	—	
		I _{OH} = -4mA		2.6	—	2.55	—	
V _{OL}	Low-Level Output Voltage	I _{OL} = 20µA	0.8V to 3.6V	—	0.1	—	0.1	V
		I _{OL} = 1.1mA	1.1V	—	0.3 x V _{CC}	—	0.3 x V _{CC}	
		I _{OL} = 1.7mA	1.4V	—	0.31	—	0.37	
		I _{OL} = 1.9mA	1.65V	—	0.31	—	0.35	
		I _{OL} = 2.3mA	2.3V	—	0.31	—	0.33	
		I _{OL} = 3.1mA		—	0.44	—	0.45	
		I _{OL} = 2.7mA	3V	—	0.31	—	0.33	
		I _{OL} = 4mA		—	0.44	—	0.45	
I _I	Input Current	A or B Input V _I = GND to 3.6V	0 to 3.6V	—	± 0.1	—	± 0.5	µA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 0V to 3.6V	0	—	0.2	—	0.6	µA
ΔI _{OFF}	Delta Power Down Leakage Current	V _I or V _O = 0V to 3.6V	0 V to 0.2V	—	0.2	—	0.6	µA
I _{CC}	Supply Current	V _I = GND or V _{CC} , I _O = 0	0.8 V to 3.6V	—	0.5	—	0.9	µA
ΔI _{CC}	Additional Supply Current	One Input at V _{CC} -0.6V Other Inputs at V _{CC} or GND	3.3V	—	40	—	50	µA

Electrical Characteristics (continued) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V_{CC}	$T_A = -40^\circ\text{C} \text{ to } +125^\circ\text{C}$		Unit
				Min	Max	
V_{IH}	High-Level Input Voltage	—	0.8V to 1.65V	$0.80 \times V_{CC}$	—	V
		—	1.65V to 1.95V	$0.70 \times V_{CC}$	—	
		—	2.3V to 2.7V	1.6	—	
		—	3.0V to 3.6V	2.0	—	
V_{IL}	Low-Level Input Voltage	—	0.8V to 1.65V	—	$0.25 \times V_{CC}$	V
		—	1.65V to 1.95V	—	$0.30 \times V_{CC}$	
		—	2.3V to 2.7V	—	0.7	
		—	3.0V to 3.6V	—	0.9	
V_{OH}	High-Level Output Voltage	$I_{OH} = -20\mu\text{A}$	0.8V to 3.6V	$V_{CC} - 0.11$	—	V
		$I_{OH} = -1.1\text{mA}$	1.1V	$0.6 \times V_{CC}$	—	
		$I_{OH} = -1.7\text{mA}$	1.4V	0.93	—	
		$I_{OH} = -1.9\text{mA}$	1.65V	1.17	—	
		$I_{OH} = -2.3\text{mA}$	2.3V	1.77	—	
		$I_{OH} = -3.1\text{mA}$		1.67	—	
		$I_{OH} = -2.7\text{mA}$	3V	2.40	—	
		$I_{OH} = -4\text{mA}$		2.30	—	
V_{OL}	Low-Level Output Voltage	$I_{OL} = 20\mu\text{A}$	0.8V to 3.6V	—	0.11	V
		$I_{OL} = 1.1\text{mA}$	1.1V	—	$0.33 \times V_{CC}$	
		$I_{OL} = 1.7\text{mA}$	1.4V	—	0.41	
		$I_{OL} = 1.9\text{mA}$	1.65V	—	0.39	
		$I_{OL} = 2.3\text{mA}$	2.3V	—	0.36	
		$I_{OL} = 3.1\text{mA}$		—	0.50	
		$I_{OL} = 2.7\text{mA}$	3V	—	0.36	
		$I_{OL} = 4\text{mA}$		—	0.50	
I_I	Input Current	$V_I = \text{GND}$ to 3.6V	0 to 3.6V	—	± 0.75	μA
I_{OFF}	Power Down Leakage Current	V_I or $V_O = 0\text{V}$ to 3.6V	0	—	± 3.5	μA
ΔI_{OFF}	Delta Power Down Leakage Current	V_I or $V_O = 0\text{V}$ to 3.6V	0V to 0.2V	—	± 2.5	μA
I_{CC}	Supply Current	$V_I = \text{GND}$ or V_{CC} , $I_O = 0$	0.8V to 3.6V	—	3.0	μA
ΔI_{CC}	Additional Supply Current	Input at $V_{CC} - 0.6\text{V}$ Other Inputs at V_{CC} or GND	3.3V	—	75	μA

Switching Characteristics

$C_L = 5\text{pF}$, See Figure 1

Parameter	From Input	TO OUTPUT	V_{CC}	$T_A = +25^\circ\text{C}$			$T_A = -40^\circ\text{C} \text{ to } +85^\circ\text{C}$		$T_A = -40^\circ\text{C} \text{ to } +125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t_{pd}	A or B	Y	0.8V	—	17.5	—	—	—	—	—	ns
			$1.2V \pm 0.1V$	2.5	5.3	11.0	2.1	12.2	2.1	13.5	
			$1.5V \pm 0.1V$	2.0	3.8	6.8	1.8	7.8	1.8	8.6	
			$1.8V \pm 0.15V$	1.6	3.1	5.3	1.4	6.2	1.4	6.9	
			$2.5V \pm 0.2V$	1.3	2.5	4.0	1.1	4.7	1.1	5.2	
			$3.3V \pm 0.3V$	1.0	2.2	3.6	1.0	4.2	1.0	4.7	

$C_L = 10\text{pF}$, See Figure 1

Parameter	From Input	TO OUTPUT	V_{CC}	$T_A = +25^\circ\text{C}$			$T_A = -40^\circ\text{C} \text{ to } +85^\circ\text{C}$		$T_A = -40^\circ\text{C} \text{ to } +125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t_{pd}	A or B	Y	0.8V	—	21.0	—	—	—	—	—	ns
			$1.2V \pm 0.1V$	2.4	6.1	13.0	2.2	14.4	2.2	15.9	
			$1.5V \pm 0.1V$	2.4	4.4	7.9	2.2	9.2	2.2	10.2	
			$1.8V \pm 0.15V$	2.0	3.7	6.2	1.9	7.3	1.9	8.1	
			$2.5V \pm 0.2V$	1.4	3.0	4.7	1.3	5.6	1.3	6.2	
			$3.3V \pm 0.3V$	1.3	2.8	4.3	1.2	4.9	1.2	5.4	

$C_L = 15\text{pF}$, See Figure 1

Parameter	From Input	TO OUTPUT	V_{CC}	$T_A = +25^\circ\text{C}$			$T_A = -40^\circ\text{C} \text{ to } +85^\circ\text{C}$		$T_A = -40^\circ\text{C} \text{ to } +125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t_{pd}	A or B	Y	0.8V	—	24.5	—	—	—	—	—	ns
			$1.2V \pm 0.1V$	3.4	6.9	14.8	3.1	16.5	3.1	18.2	
			$1.5V \pm 0.1V$	2.8	5.0	8.9	2.5	10.5	2.5	11.6	
			$1.8V \pm 0.15V$	2.0	4.1	7.0	2.0	8.3	2.0	9.2	
			$2.5V \pm 0.2V$	1.7	3.5	5.3	1.5	6.4	1.5	7.1	
			$3.3V \pm 0.3V$	1.6	3.2	4.9	1.4	5.7	1.4	6.3	

$C_L = 30\text{pF}$, See Figure 1

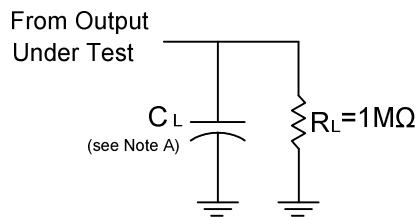
Parameter	From Input	TO OUTPUT	V_{CC}	$T_A = +25^\circ\text{C}$			$T_A = -40^\circ\text{C} \text{ to } +85^\circ\text{C}$		$T_A = -40^\circ\text{C} \text{ to } +125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t_{pd}	A or B	Y	0.8V	—	34.8	—	—	—	—	—	ns
			$1.2V \pm 0.1V$	4.6	17.5	22.0	4.1	22.6	4.1	24.9	
			$1.5V \pm 0.1V$	3.0	6.5	11.8	2.9	14.0	2.9	15.4	
			$1.8V \pm 0.15V$	2.6	5.4	9.3	2.3	11.1	2.3	12.3	
			$2.5V \pm 0.2V$	2.4	4.6	7.1	2.1	8.5	2.1	9.4	
			$3.3V \pm 0.3V$	2.3	2.6	6.5	2.1	7.6	2.1	8.4	

Operating and Package Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Parameter		Test Conditions		V _{CC}	Typ	Unit
C_{pd}	Power Dissipation Capacitance	$f = 1\text{MHz}$ No Load		0.8V	6.5	pF
				1.2V $\pm 0.1\text{V}$	6.3	
				1.5V $\pm 0.1\text{V}$	6.3	
				1.8V $\pm 0.15\text{V}$	6.2	
				2.5V $\pm 0.2\text{V}$	6.2	
				3.3V $\pm 0.3\text{V}$	6.1	
C_i	Input Capacitance	$V_i = V_{CC}$ or GND		0V or 3.3V	1.5	pF
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT353	(Note 9)	—	371	°C/W
		X2-DFN0808-4		—	430	
		X1-DFN1010-6		—	435	
		X2-DFN1010-6		—	445	
		X2-DFN1409-6		—	470	
		X2-DFN1410-6		—	460	
θ_{JC}	Thermal Resistance Junction-to-Case	SOT353	(Note 9)	—	143	°C/W
		X2-DFN0808-4		—	240	
		X1-DFN1010-6		—	250	
		X2-DFN1010-6		—	250	
		X2-DFN1409-6		—	275	
		X2-DFN1410-6		—	265	

Note: 9. Test condition for each of the six package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Parameter Measurement Information



V _{CC}	Inputs		V _M	C _L
	V _I	t _{r/t_f}		
0.8V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF
1.2V±0.1V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF
1.5V±0.1V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF
1.8V±0.15V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF
2.5V±0.2V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF
3.3V±0.3V	V _{CC}	≤3ns	V _{CC} /2	5, 10, 15, 30pF

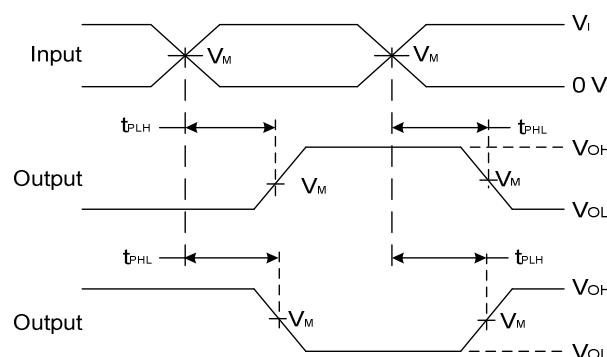
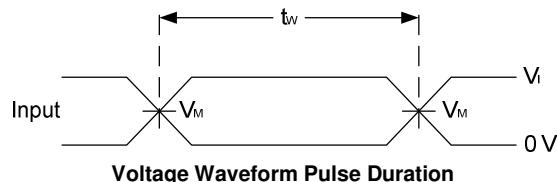


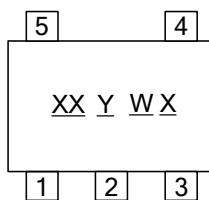
Figure 1 Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate $\leq 10\text{MHz}$.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD}.

Marking Information

(1) SOT353

(Top View)

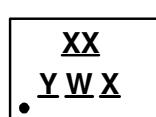


XX : Identification code
Y : Year 0~9
W : Week : A~Z : 1~26 week;
 a~z : 27~52 week; z represents
 52 and 53 week
X : A~Z : Internal code

Part Number	Package	Identification Code
74AUP1G00SE-7	SOT353	XH

(2) X2-DFN0808-4, X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6 and X2-DFN1410-6

(Top View)

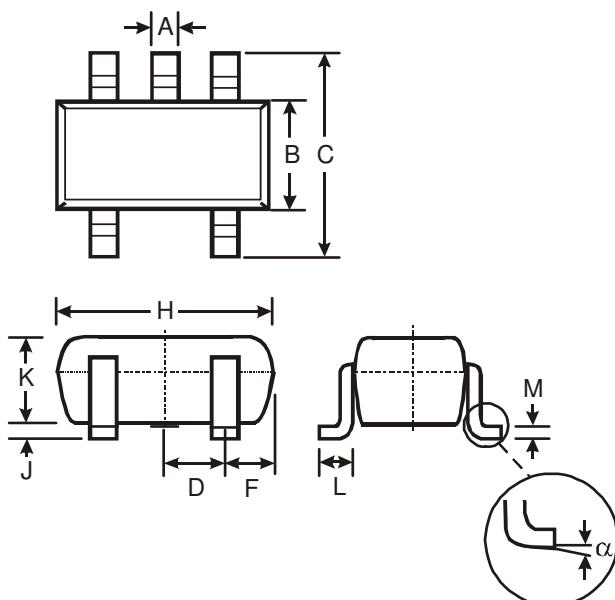


XX : Identification Code
Y : Year : 0~9
W : Week : A~Z : 1~26 week;
 a~z : 27~52 week; z represents
 52 and 53 week
X : A~Z : Internal code

Part Number	Package	Identification Code
74AUP1G00FS3-7	X2-DFN0808-4	YJ
74AUP1G00FW5-7	X1-DFN1010-6	Q1
74AUP1G00FW4-7	X2-DFN1010-6	XH
74AUP1G00FX4-7	X2-DFN1409-6	HA
74AUP1G00FZ4-7	X2-DFN1410-6	XH

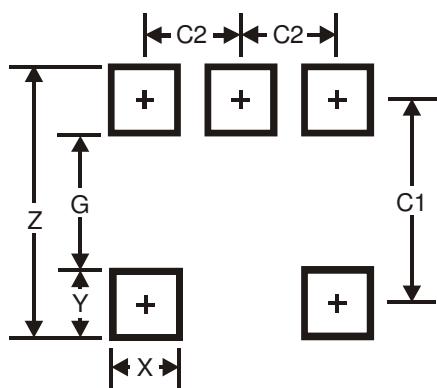
SOT353 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT353			
Dim	Min	Max	Typ
A	0.10	0.30	0.25
B	1.15	1.35	1.30
C	2.00	2.20	2.10
D	0.65	Typ	
F	0.40	0.45	0.425
H	1.80	2.20	2.15
J	0	0.10	0.05
K	0.90	1.00	1.00
L	0.25	0.40	0.30
M	0.10	0.22	0.11
α	0°	8°	-

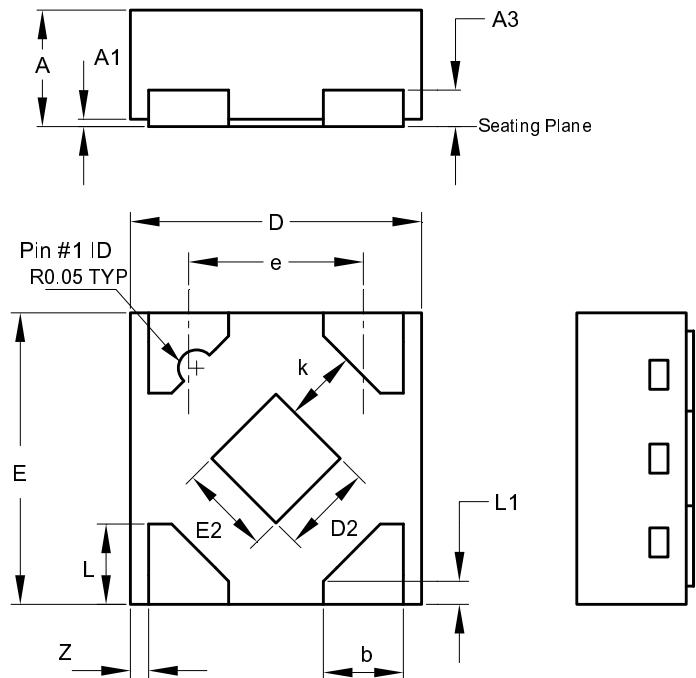
All Dimensions in mm



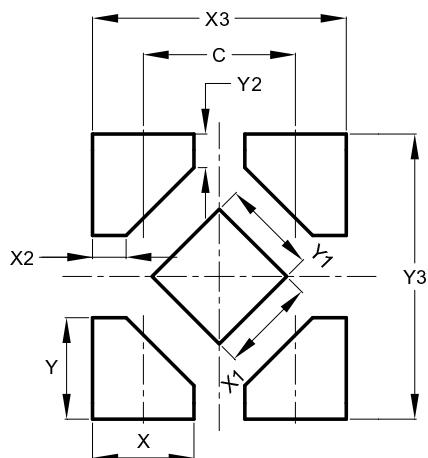
Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

X2-DFN0808-4 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



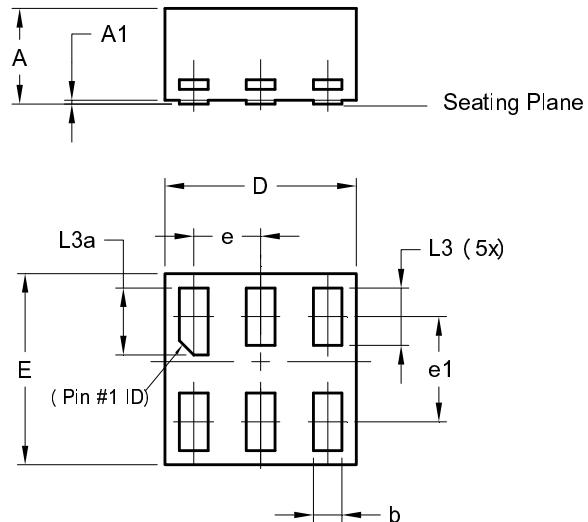
X2-DFN0808-4			
Dim	Min	Max	Typ
A	0.25	0.35	0.30
A1	0	0.04	0.02
A3	-	-	0.13
b	0.17	0.27	0.22
D	0.75	0.85	0.80
D2	0.15	0.35	0.25
E	0.75	0.85	0.80
E2	0.15	0.35	0.25
e	-	-	0.48
k	0.20	-	-
L	0.17	0.27	0.22
L1	0.02	0.12	0.07
z	-	-	0.05
All Dimensions in mm			



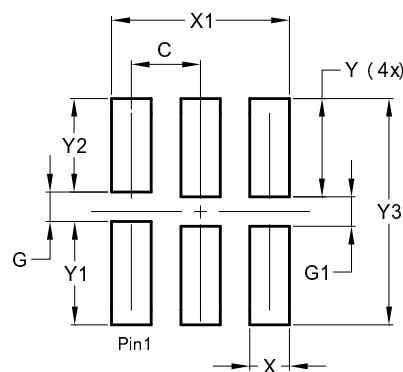
Dimensions	Value
C	0.480
X	0.320
X1	0.300
X2	0.106
X3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900

X1-DFN1010-6 (Type B) Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



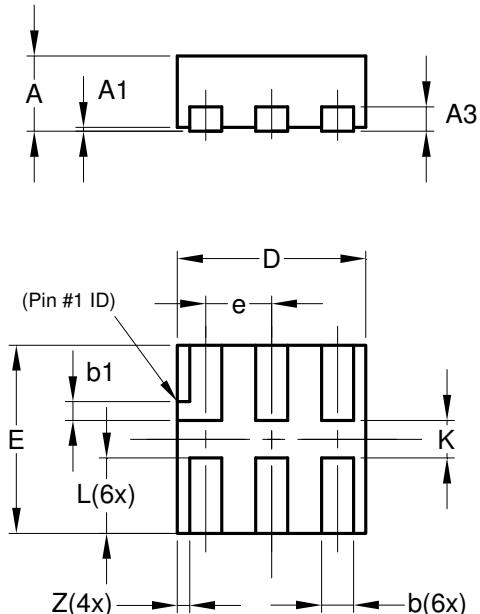
X1-DFN1010-6 (Type B)			
Dim	Min	Max	Typ
A	-	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
E	0.95	1.050	1.00
e	0.35	BSC	
e1	0.55	BSC	
L3	0.27	0.30	0.30
L3a	0.32	0.40	0.35
All Dimensions in mm			



Dimensions	Value (in mm)
C	0.350
G	0.150
G1	0.150
X	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

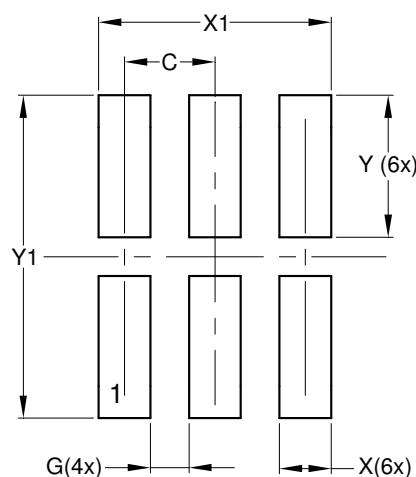
X2-DFN1010-6 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065

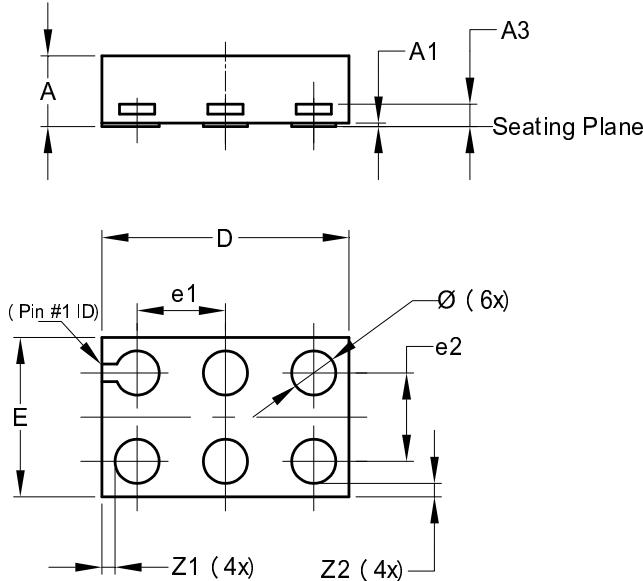
All Dimensions in mm



Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

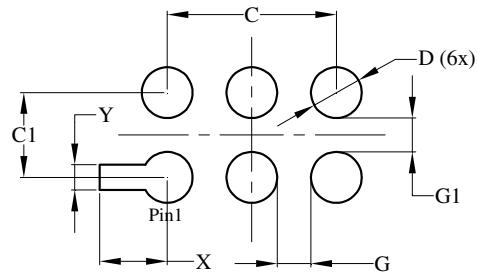
X2-DFN1409-6 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X2-DFN1409-6			
Dim	Min	Max	Typ
A	-	0.40	0.39
A1	0	0.05	0.02
A3	-	-	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	-	-	0.50
e2	-	-	0.50
Z1	-	-	0.075
Z2	-	-	0.075

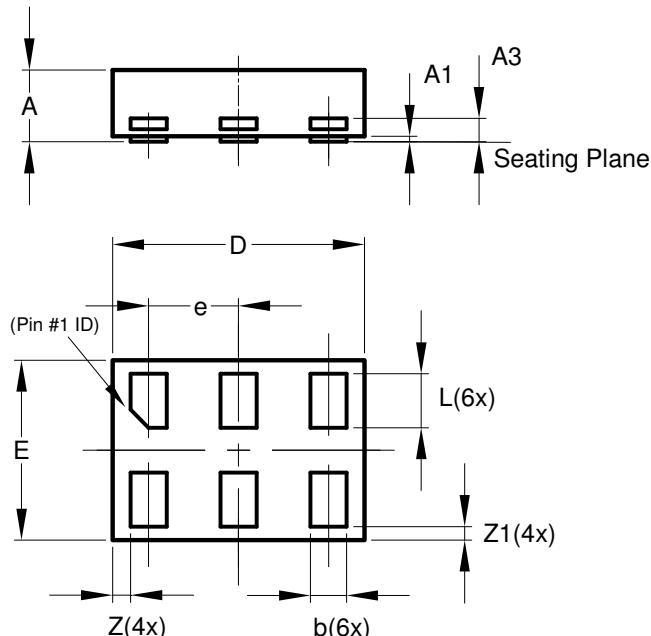
All Dimensions in mm



Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

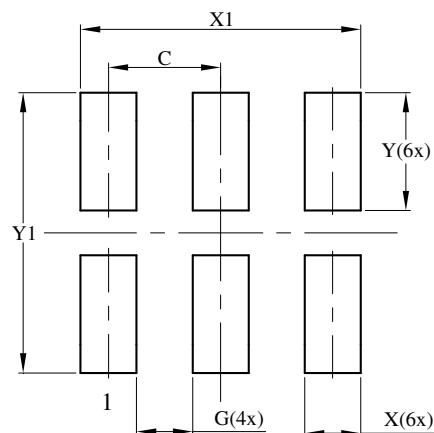
X2-DFN1410-6 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075

All Dimensions in mm



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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ООО "ЛайфЭлектроникс"

"LifeElectronics" LLC

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

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С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибуторских договоров

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- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
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- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

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- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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